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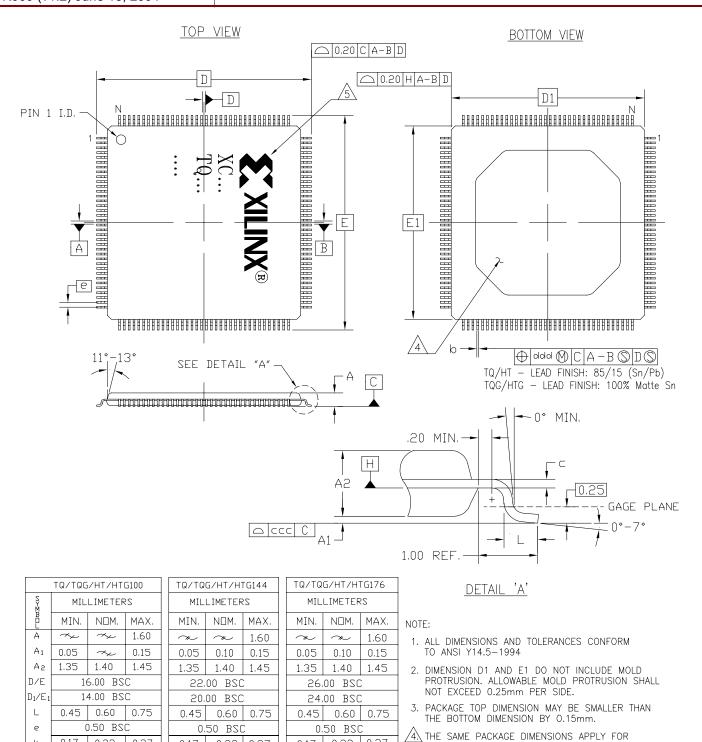
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TQFP (TQ144/TQG144) Package



THERMALLY ENHANCED PRODUCTS. HEAT SINK IS ADDED. THE PACKAGE CODE IS "HT" HEAT SINK DIMENSIONS: HT100=10.0mm SQ. REF. HT144=15.5mm SQ. REF. HT176=19.4mm SQ. REF.

 $\sqrt{5}$ MARK ORIENTATION WITH RESPECT TO PIN-1 I.D. IF 2 OR MORE CIRCLES EXIST ON TOP OF THE PACKAGE, USE THE SMALLEST CIRCLE AS PIN-1 I.D.

100, 144, and 176-PIN TQFP (TQ100/TQG100, TQ144/TQG144, and TQ176/TQG176) 100, 144, and 176-PIN HEAT SINK TQFP (HT100/HTG100, HT144/HTG144, and HT176/HTG176)

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176

JEDEC MS-026-BGA

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